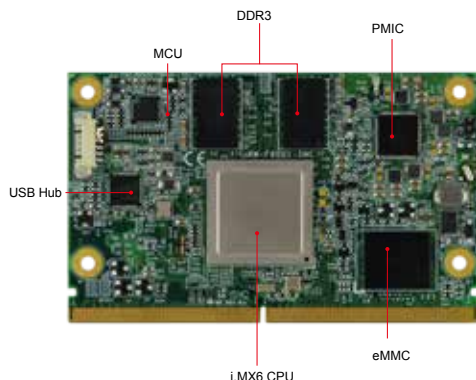


RM-F6 series

Wide Temperature SMARC Module w/ NXP i.MX6 Cortex-A9 800MHz SoC



Features

- SMARC Small Form Factor (82mm x 50mm) SoM
- i.MX6 automotive-grade Dual/Solo core 800MHz
- 1080p hardware encode/decode
- OpenGL ES 2.0 and OpenVG 1.1 hardware accelerators
- 1GB DDR3, 4GB eMMC on board
- 10/100/1000 Mbit Ethernet
- Supports 24-bit parallel LCD, LVDS & HDMI
- Supports Linux 3.0, Android 4.3
- Wide-range operating temperature (-40°C~85°C)

System

Form Factor	SMARC™
CPU	NXP i.MX6 Dual/ Solo Cortex-A9 Up to 800Mhz with 512KB L2 cache
System Memory	I-grade 1GB DDR3 on board
Display	Supports 18/24-bit parallel LCD & LVDS Interface (Up to 1366 x 768) Supports HDMI Interface (1920 x 1080)
Video Codec	Multi-format HD1080 video Decode and Encode
Audio Interface	I²S, SPDIF
LAN	AR8031 LAN PHY on board
USB	2x USB 2.0 port & 1x USB OTG Interface
Image Capture Interface	CSI Interface for MIPI camera
Serial	4x UART, 1x SPI Interface
Media Interface	2x High-speed MMC/SDIO (MMC 8-bit, SDIO 4-bit)
PCI-E	1x PCI-E interface
SATA	1x SATA 2.0 (Dual only)
GPIO	12x GPIO
I²C	3x I²C *(4x I²C in F6SO1)
CAN Bus	2x CAN2.0B
Dimensions	82mm x 50mm (3.2" x 2")

Environment	Humidity: 0 % to 90 % RH at 60° C (non-condensing) Shock: Non-Operating: 1G, 15 mins (x-, y-, z-axis) Vibration : Non-operating: 3 Hz to 500 Hz, 15 mins
Operating Temperature	-40°C to +85°C (*need heat-sink solution)
Software Support	Ubuntu Linux 11.10 (kernel 3.0)/ Android 4.3
Certification	CE/ FCC Class A

Ordering Information

RM-F6DU1-SMC	RISC System on Module, 82mm x 50mm, SMARC small form factor with onboard NXP i.MX6 Dual 800MHz CPU, 1GB DDR3, 4GB eMMC, -40°C~85°C operating temperature
RM-F6SO1-SMC	RISC System on Module, 82mm x 50mm, SMARC small form factor with onboard NXP i.MX6 Solo 800MHz CPU, 1GB DDR3, 4GB eMMC, -40°C~85°C operating temperature
F6DU1-HSD	Heat spreader for F6DU1
F6SO1-HSD	Heat spreader for F6SO1
F6Sxx-HSK	Heat sink for F6DU1-HSD an F6SO1-HSD